

ABSTRACT

A printed circuit board 2 and an FPC board 3 to be connected together are each given a multilayer structure wherein insulating films 23, 33 and interconnection patterns 22, 32 are stacked alternately. In the FPC board 3, connecting signal lines are distributed among the multilayered interconnection patterns 22, and in the printed circuit board 2, interconnecting to lands 32a formed on a connection face thereof is carried out using interconnection patterns 32 of inner layers. By this means, it is possible to greatly increase the number of connecting signal lines between the printed circuit board 2 and the FPC board 3.